# The current waveform in reactive high power impulse magnetron sputtering

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4<sup>th</sup> Magnetron, Ion processing & Arc Technologies European Conference, 14<sup>th</sup> International Symposium on Reactive Sputter Deposition, Paris, France December 11, 2015

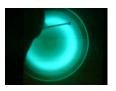




#### Introduction







- Magnetron sputtering has been the workhorse of plasma based sputtering methods for over four decades
- For many applications a high degree of ionization of the sputtered vapor is desired
  - controlled ion bombardment of the growing film controlled by a negative bias applied to the substrate
  - collimation enhanced step coverage
- Common to all highly ionized magnetron sputtering techniques is a very high density plasma

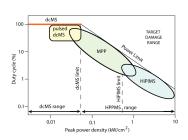






#### Introduction

- In a conventional dc magnetron discharge the power density is limited by the thermal load on the target
- High power pulsed magnetron sputtering (HPPMS)
- In a HiPIMS discharge a high power pulse is supplied for a short period
  - low frequency
  - low duty cycle
  - low average power



From Gudmundsson et al. (2012), JVSTA 30 030801

Power density limits
p<sub>t</sub> = 0.05 kW/cm<sup>2</sup> dcMS limit
p<sub>t</sub> = 0.5 kW/cm<sup>2</sup> HiPIMS limit







#### Introduction

- Reactive sputtering, where metal targets are sputtered in a reactive gas atmosphere to deposit compound materials is of utmost importance in various technologies
- In reactive sputtering processes a reactive gas O<sub>2</sub>, N<sub>2</sub>, or CH<sub>4</sub> etc. is mixed to the noble working gas for oxide, nitride, or carbide deposition
- The high electron density in the HiPIMS discharge is expected to enhance the dissociation of the molecular gas







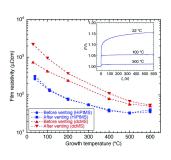
## Reactive HiPIMS - Applications





#### Application - Film Resistivity

- TiN as diffusion barriers for interconnects
- HiPIMS deposited films have significantly lower resistivity than dcMS deposited films on SiO<sub>2</sub> at all growth temperatures due to reduced grain boundary scattering
- Thus, ultrathin continuous TiN films with superior electrical characteristics and high resistance towards oxidation can be obtained with HiPIMS at reduced temperatures



From Magnus et al. (2012) IEEE EDL 33 1045

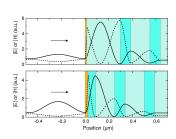






#### Application – Bragg mirror

- Multilayer structures containing a high-contrast (TiO<sub>2</sub>/SiO<sub>2</sub>) Bragg mirror fabricated on fused-silica substrates
  - reactive HiPIMS TiO<sub>2</sub> (88 nm)
  - reactive dcMS SiO<sub>2</sub> (163 nm)
  - capped with semitransparent gold
- Rutile TiO<sub>2</sub> (n = 2.59) and SiO<sub>2</sub> (n = 1.45) provide a large index contrast
- Smooth rutile TiO<sub>2</sub> films can be obtained by HiPIMS at relatively low growth temperatures, without post-annealing



From Leosson et al. (2012) Opt. Lett. 37 4026



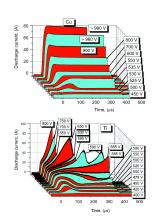


## Reactive HiPIMS - Voltage - Current - Time characteristics





- In non-reactive discharge the current waveform shows an initial pressure dependent peak that is followed by a second phase that is power and material dependent
- The initial phase is dominated by gas ions, whereas the later phase has a strong contribution from self-sputtering
- For some materials, the discharge switches into a mode of sustained self-sputtering



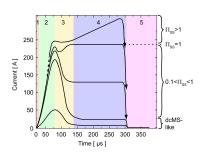
From Anders et al. (2007),

JAP 102 113303 and JAP 103 039901





- A schematic illustration of the discharge current assuming square shaped voltage pulses
- The current is generally characterized by an initial peak followed by a more or less stable current plateau (bottom current curves)
- In other cases it shows an initial peak followed by a second increase of the discharge current (top current curves)
- The non-reactive case is well understood



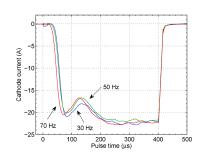
From Gudmundsson et al. (2012), JVSTA 30 030801







- Ar discharge with Ti target
- The initial peak in current results large flux of atoms from the target
- Collisions of the sputtered atoms with the working gas result in heating and expansion of the working gas – rarefaction
- A significant fraction of the sputtered atoms experience electron impact ionization (the ionization mean free path ~ 1 cm) and are attracted back to the target to participate in the sputtering process – self-sputtering



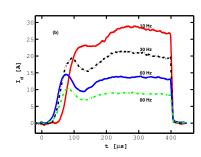
From Magnus et al. (2011) JAP 110 083306







- During reactive sputtering, a reactive gas is added to the inert working gas
- The current waveform in the reactive Ar/N<sub>2</sub> HiPIMS discharge is highly dependent on the pulse repetition frequency, unlike for pure Ar
- N<sub>2</sub> addition changes the plasma composition and the target condition can also change due to the formation of a compound on its surface



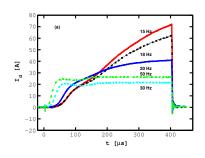
After Magnus et al. (2011) JAP 110 083306







- Similarly for the Ar/O<sub>2</sub>
   discharge, the current
   waveform is highly dependent
   on the repetition frequency and
   applied voltage which is linked
   to oxide formation on the target
- The current is found to increase significantly as the frequency is lowered



After Magnus et al. (2012), JVSTA 30 050601

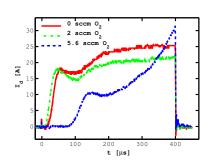






- As the oxygen flow is increased a transition to oxide mode is observed – The delay in the onset of the current increases, the initial current peak is lowered and a transition to a self-sputtering runaway occurs
- It has been confirmed that in the oxide mode, the discharge is dominated by O<sup>+</sup>-ions, due to oxygen atoms sputtered off the target surface

Aiempanakit et al. (2013), JAP 113 133302



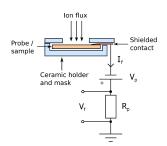
The current waveforms for an  $Ar/O_2$  discharge with a Ti target where the oxygen flow rate is varied – 600 V, 50 Hz and 0.6 Pa

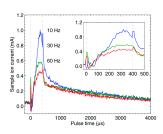
From Gudmundsson et al. (2013), ISSP 2013, p. 192

Gudmundsson (2016) Plasma Phys. Contr. Fus. 58 01400



 The observed changes in the discharge current are reflected in the flux of ions impinging on the substrate

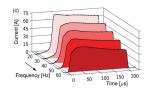


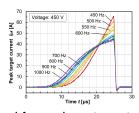


From Magnus et al. (2011), JAP 110 083306









- Similar behaviour has been reported for various target and reactive gas combinations
  - The current increases with decreased repetition frequency
  - The current waveform maintains its shape for Ar/O<sub>2</sub> discharge with Nb target

From Hála et al. (2012), JPD 45 055204

 The current waveform becomes distinctly triangular for Ar/N<sub>2</sub> discharge with Hf target

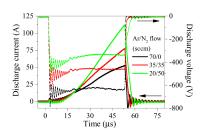


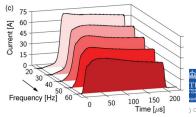
- The current increases with increased partial pressure of the reactive gas
  - The current waveform becomes distinctly triangular for Ar/N<sub>2</sub> discharge with Al target

From Moreira et al. (2015), JVSTA 33 021518

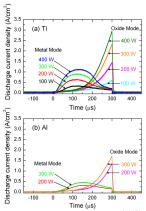
 The current waveform maintains its shape for Ar/O<sub>2</sub> discharge with Nb target

From Hála et al. (2012), JPD 45 055204

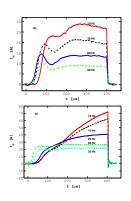




- The shape of the current waveform depends on the mode of operation
  - The current waveform becomes distinctly triangular for Ar/O<sub>2</sub> dischage with both Al and Ti target

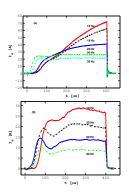


- HiPIMS differs significantly from dcMS, due to the fact that self-sputtering quickly becomes dominant and the working gas ions (mostly Ar<sup>+</sup> and N<sub>2</sub><sup>+</sup> or O<sub>2</sub><sup>+</sup>) are depleted from the area in front of the target, due to rarefaction
- The secondary electron emission yield is governed by the composition of the target (Ti or TiN or TiO<sub>2</sub>) and the type of ions that are bombarding it



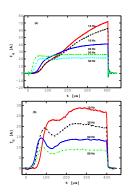
After Magnus et al. (2011), JAP **110** 083306 and Magnus et al. (2012), JVSTA **30** 05064KTH

- $\gamma_{\rm see}$  is practically zero for singly charged metal ions impacting a target of the same metal
- $\gamma_{\rm see}$  will be higher for self sputtering from a TiN or TiO<sub>2</sub> target, where N<sup>+</sup>-ions or O<sup>+</sup>-ions are also present, than for self-sputtering from a Ti target, where multiply charged Ti ions are needed to create secondary electrons



After Magnus et al. (2011), JAP **110** 0823306 and Magnus et al. (2012), JVSTA **30** 05056 ETH

- At high frequencies, nitride or oxide is not able to form between pulses, and self-sputtering by Ti<sup>+</sup>-ions (singly and multiply charged) from a Ti target is the dominant process
- At low frequency, the long off-time results in a nitride or oxide layer being formed on the target surface and self-sputtering by Ti<sup>+</sup>- and N<sup>+</sup>-ions or O<sup>+</sup>-ions from TiN or TiO<sub>2</sub> takes place



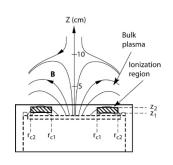
From Magnus et al. (2011), JAP **110** 083306 and Magnus et al. (2012), JVSTA **30** 050

Gudmundsson (2016) PPCF 58 014002





- The ionization region model (IRM) was developed to improve the understanding of the plasma behaviour during a HiPIMS pulse and the afterglow
- The main feature of the model is that an ionization region (IR) is defined next to the race track
- The IR is defined as an annular cylinder with outer radii  $r_{c2}$ , inner radii  $r_{c1}$  and length  $L = z_2 z_1$ , extends from  $z_1$  to  $z_2$  axially away from the target



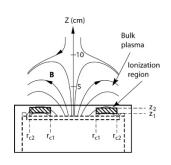
The definition of the volume covered by the IRM From Raadu et al. (2011), PSST **20** 065007







- Geometrical effects are included indirectly as loss and gain rates across the boundaries of this annular cylinder to the target and the bulk plasma
- The temporal development is defined by a set of ordinary differential equations giving the first time derivatives of the electron energy and the particle densities for all the particles
- The electron density is found assuming quasi-neutrality of the plasma



The definition of the volume covered by the IRM From Raadu et al. (2011), PSST **20** 065007



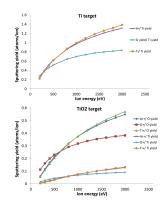




- The species assumed in the IRM are
  - electrons
  - argon atoms Ar(3s<sup>2</sup>3p<sup>6</sup>), warm argon atoms in the ground state Ar<sup>W</sup>, hot argon atoms in the ground state Ar<sup>H</sup>, Ar<sup>m</sup> (1s<sub>5</sub> and 1s<sub>3</sub>) (11.6 eV), argon ions Ar<sup>+</sup> (15.76 eV), doubly ionized argon ions Ar<sup>2+</sup> (27.63 eV)
  - titanium atoms Ti(a<sup>3</sup>F), titanium ions Ti<sup>+</sup> (6.83 eV), doubly ionized titanium ions Ti<sup>2+</sup> (13.58 eV)
  - oxygen molecule in the ground state  $O_2(X^3\Sigma_g^-)$ , the metastable oxygen molecules  $O_2(a^1\Delta_g)$  (0.98 eV) and  $O_2(b^1\Sigma_g)$  (1.627 eV), the oxygen atom in the ground state  $O(^3P)$ , the metastable oxygen atom  $O(^1D)$  (1.96 eV), the positive ions  $O_2^+$  (12.61 eV) and  $O^+$  (13.62 eV), and the negative ion  $O^-$

Toneli et al. (2015) J. Phys. D. 48 325202

- The sputter yield for the various bombarding ions was calculated by TRIDYN for
  - Metal mode Ti target
  - Poisoned mode TiO<sub>2</sub> target
- The yields correspond to the extreme cases of either clean Ti surface and a surface completely oxidized (TiO<sub>2</sub> surface)

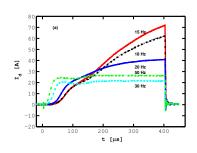


The sputter yield data is from Tomas Kubart,
Uppsala University





- The model is applied to explore Ar/O<sub>2</sub> discharge with Ti target in both metal mode and oxide (poisoned) mode
- The IRM is a semi-empirical model in the sense that it uses a measured discharge current waveform as a main input parameter
- For this study we use the measured curve for Ar/O<sub>2</sub> with Ti target at 50 Hz for metal mode and at 15 Hz for poisoned mode



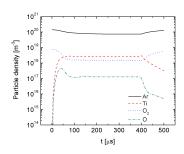
After Magnus et al. (2012), JVSTA 30 050601







- The gas rarefaction is observed for the argon atoms but is more significant for the O<sub>2</sub> molecule
- The density of Ti atoms is higher than the O<sub>2</sub> density
- The atomic oxygen density of is over one order of magnitude lower than the molecular oxygen density – the dissociation fraction is low

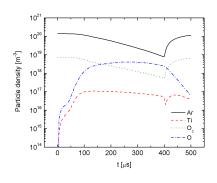


The temporal evolution of the neutral species with 5 % oxygen partial flow rate for Ar/O<sub>2</sub> discharge with Ti target in metal mode.





- Gas rarefaction is observed for both argon atoms and O<sub>2</sub> molecules
- The density of Ti atoms is lower than both the O<sub>2</sub> density and atomic oxygen density
- The atomic oxygen density is higher than the O<sub>2</sub> density in towards the end of the pulse



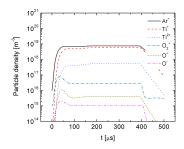
The temporal evolution of the neutral species with 5 %

oxygen partial flow rate for Ar/O<sub>2</sub> discharge with Ti target in poisoned mode.





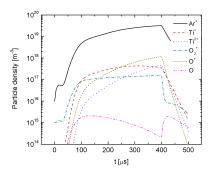
- Ar<sup>+</sup> and Ti<sup>+</sup>-ions dominate the discharge
- Ti<sup>2+</sup>-ions follow by roughly an order of magnitude lower density
- The O<sub>2</sub><sup>+</sup> and O<sup>+</sup>-ion density is much lower



The temporal evolution of the neutral species with 5 % oxygen partial flow rate for Ar/O<sub>2</sub> discharge with Ti target in metal mode.



- Ar<sup>+</sup>-ions dominate the discharge
- Ti<sup>+</sup>, O<sup>+</sup>, have very similar density, but the temporal variation is different, and the O<sub>2</sub><sup>+</sup> density is slightly lower
- The Ti<sup>2+</sup>-ion density increases fast with time and overcomes the Ti<sup>+</sup> density towards the end of the pulse



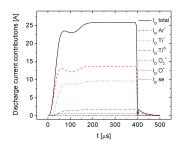
The temporal evolution of the neutral species with 5 %

oxygen partial flow rate for Ar/O<sub>2</sub> discharge with Ti target in poisoned mode.



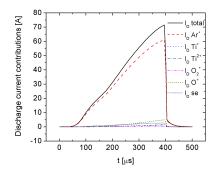


 Ar<sup>+</sup> and Ti<sup>+</sup>-ions contribute most significantly to the discharge current



The temporal evolution of the neutral species with 5 % oxygen partial flow rate for  ${\rm Ar}/{\rm O}_2$  discharge with Ti target in metal mode.

- Ar<sup>+</sup> contribute most significantly to the discharge current – almost solely
- The contribution of secondary electron emission is very small



The temporal evolution of the neutral species with 5 %

**oxygen partial flow** rate for Ar/O<sub>2</sub> discharge with Ti target in **poisoned mode**.





## Summary





#### **Summary**

- The current-voltage-time waveforms in a reactive discharge exhibit similar general characteristics as the non-reactive case in some cases
  - the current rises to a peak, then decays because of rarefaction before rising to a self-sputtering dominated phase
  - in other cases the current develops a triangular shape as repetition frequency is lowered or the partial pressure of the reactive gas is increased
- At low repetition frequency, the long off-time results in a nitride or oxide layer being formed on the target surface and an increase in the discharge current





#### **Summary**

- An ionization region model was used to explore the plasma composition during the high power pulse
- Comparison was made between the metal mode and the poisoned mode
  - In metal mode Ar<sup>+</sup> and Ti<sup>+</sup>-ions dominate the discharge and are of the same order of magnitude
  - In poisoned mode Ar<sup>+</sup>-ions dominate the discharge and two orders of magnitude lower, Ti<sup>+</sup>, O<sup>+</sup>, have very similar density, with the O<sub>2</sub><sup>+</sup> density slightly lower
  - In the metal mode Ar<sup>+</sup> and Ti<sup>+</sup>-ions contribute most significantly to the discharge current while in poisoned mode Ar<sup>+</sup> dominate
- Ar<sup>+</sup>-ions are responsible for the increase in the discharge current in poisoned mode



#### The slides can be downloaded at

http://langmuir.raunvis.hi.is/~tumi/hipims.html

- The experimental work was made in collaboration with
  - Dr. Fridrik Magnus, Uppsala University, Uppsala, Sweden
  - Tryggvi K. Tryggvason, University of Iceland
- The modeling work is in collaboration with
  - Dr. Daniel Lundin, Université Paris-Sud, Orsay, France
  - Prof. Nils Brenning, KTH Royal Institite of Technology, Stockholm, Sweden
  - Prof. Tiberu Minea, Université Paris-Sud, Orsay, France
- We got help with the sputtering yields from
  - Dr. Tomas Kubart, Uppsala University, Uppsala, Sweden
- and the project is funded by
  - Icelandic Research Fund Grant No. 130029-053
  - Swedish Government Agency for Innovation Systems (VINNOVA) contract no. 2014-04876,



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